

## C2160B

### Conductor

#### Description

C2160B is a Pd/Ag composition designed for hybrid applications and application where more leach resistance is required. The C2160B conductor is suitable for a wide variety of applications such as automotive electronics, power hybrids and commercial applications where more stringent requirements exist. It exhibits excellent solderability, aged adhesion and is aluminium wire bondable.

#### Key Features

- Excellent solderability and leach resistance
- Excellent long term adhesion
- Good Al wire bond adhesion (initial and aged)



*This picture does not show the packaging of C2160B and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

Viscosity	150-220 Kcps Brookfield HBTSC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Solids	79.0 ± 1.0 %
Alloy Ratio	06:01
Coverage	80 cm <sup>2</sup> /g at 12 um fired film thickness
Metal	AgPd
Color	Dark Grey

#### Recommended Processing Guide

Process Temperature (TDS)	850 °C peak temperature. 10 minutes at peak. Total cycle time 30-60 minutes.
Film Thickness	10-15 um

C2160B

Conductor

Warranty

6 months

Americas

Phone +1 610 825 6050  
electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649  
electronics.apac@heraeus.com

China

Phone +86 53 5815 9601  
electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370  
electronics.emea@heraeus.com

The descriptions and engineering data shown here have been compiled by Heraeus using commonly accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo and Heraeus, figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.